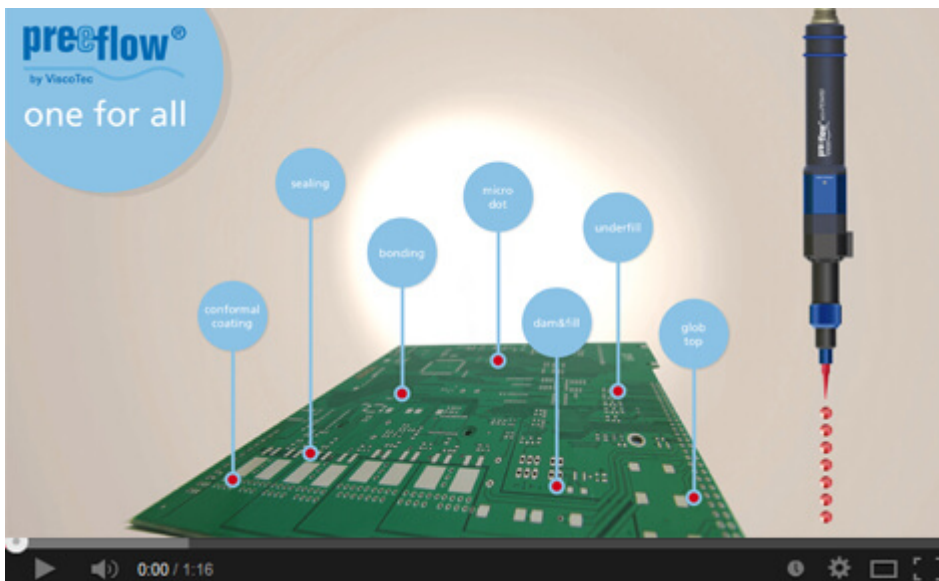


preflow micro-dispensing for electronics manufacturing

We have previously discussed [the need for greater precision and repeatability of adhesive dispensing](#) within ever smaller and denser pcb real estate in the world of electronics assembly and manufacturing. Applications include optical bonding (e.g. touch screens, displays, smartphones, tablets), conformal coating, encapsulation (either dam & fill or glob top), underfills, and the like. There are many other applications where micro-dispensing (amounts of less than a few microlitres) of adhesives or protective materials is needed.

[Here is a video which explains more!](#)



preeflow micro-dispensing for electronics manufacturing

Supplied by:

intertronics

INTERTRONICS

12a Station Field Industrial Estate, Banbury Road, Kidlington

Oxfordshire England OX5 1JD

t 01865 842842 e info@intertronics.co.uk

Last updated: November 2018

Statements, technical information and recommendations contained herein are based on tests we believe to be reliable but they are not to be construed in any manner as warranties expressed or implied. The user shall determine the suitability of the product for his intended use and the user assumes all risk and liability whatsoever in connection therewith.